

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

SSOP

(printed on: 2020-07-11 20:40:18)

**TOTAL MASS (g) : 0.079989**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001488	1000000	18602.5410156		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000062	1000000	775.105834961		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.029933	975000	374213.59375		
		Iron (Fe)	7439-89-6	0.000737	24000	9213.75878906		
		Phosphorus (P)	7723-14-0	0.000009	300	112.515365601		
		Zinc (Zn)	7440-66-6	0.000021	700	262.535858154		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.030700</b>	<b>1000000</b>	<b>383802.40625</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.002272	1000000	28404.8808594		
		<b>External Plating Total:</b>				<b>0.002272</b>	<b>1000000</b>	<b>28404.8808594</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000246	1000000	3075.42016602		
<b>Internal Plating Total:</b>				<b>0.000246</b>	<b>1000000</b>	<b>3075.42016602</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000565	750000	7063.46435547		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000188	250000	2350.32104492		
<b>Die Attach Total:</b>				<b>0.000753</b>	<b>1000000</b>	<b>9413.78515625</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.006605	150000	82573.7734375		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.036105	820000	451374.15625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.001101	25000	13764.3798828		
		Carbon Black (C)	1333-86-4	0.000220	5000	2750.37548828		
		<b>Encapsulation Total:</b>				<b>0.044031</b>	<b>1000000</b>	<b>550462.6875</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000437	1000000	5463.24609375		
					<b>TOTAL MASS (g) :</b>	<b>0.079989</b>		